

THE PROBLEM

Modern chips are intricate 3D stacks. Diagnosing yield problems means mapping what sits inside them, in 3D. Today that is days of work for a PhD specialist on a multi-million-euro microscope, so labs inspect only a fraction of what they need to.

WHAT RAYNETICS DOES

Advanced 3D imaging and reconstruction software for the chip industry. Our physics-aware AI turns those days of specialist work into a one-hour automated job any operator can run, so labs see far more with the microscopes they already own. One platform across TEM, FIB-SEM and X-ray.

FASTER TURNAROUND	PHDS IN THE LOOP	SOFTWARE STACK	CUSTOMER SOVEREIGNTY
10x Days of expert work compressed to under an hour.	0 Any operator runs it. The talent bottleneck disappears.	1 Covers most 3D volumetric chip-inspection tools. TEM, FIB-SEM, X-ray.	100% Model learns only from your data. No cross-client training

01 Validation and commercial pipeline

ZEISS MICROSCOPY	LoI signed as 3D imaging software partner for their FIB-SEM & TEM instruments. Joint paper on inline 3D chemical imaging , with talks at IMC21 Liverpool and EU-FIB Marseille .	LOI SIGNED
US TIER-1 IDM	3D reconstructions on a 5nm production-quality dataset shared and now in customer validation. Paid pilot to close by end of 2026. NDA.	VALIDATING
EM OEM, TOP 3 GLOBAL	Validated on a 22nm FinFET dataset . Joint abstract at ISTFA 2026 .	PUBLIC
AMSTERDAM SCIENTIFIC INSTRUMENTS	3D imaging software for their Cheetah detectors (TEM). Grant-funded co-development (PULS3M).	SIGNED
DELMIC	Wafer-scale defect segmentation for power semiconductors via cathodoluminescence microscopy. Joint Eurostars in preparation.	PARTNERSHIP

DILUTIVE SECURED CLAs from Innovatiefonds Noord-Holland and an angel investor.	NON-DILUTIVE SECURED €300k Holland High Tech · €100k MIT R&D · €40k MIT Feasibility 2025/26 · €20k WBSO. Eurostars with Delmic in prep.	INTELLECTUAL PROPERTY Patent on method & workflow filed . Algorithm as trade secret .
€375k	€460k	July 2026

MARKET

Semi metrology & FA software

Adjacent to the \$13–15B semiconductor process-control market, expanding with advanced nodes.

BUSINESS MODEL

SaaS. Per-seat & per-dataset

Recurring software revenue. OEM licensing as long-tail upside.

GO-TO-MARKET

Service labs > OEMs > IDMs

Anchored at HTC Eindhoven and Bay Area. IMC and ISTFA stage in 2026.

02 Team and advisors

Ajinkya Kadu, PhD **CEO** Nanoscale 3D imaging. ex-CWI, ex-MERL, ex-Antwerp. PhD Utrecht.

Mritunjay Prasad **CTO** AI / ML. Research fellow CMU, ISRO. IIT Bombay alum.

Maadhav Kothari, PhD **CCO** Material Scientist. ex-Zeiss. TPM at CZI Biohub. PhD St. Andrews.

Naiara Larreina, PhD **APPLIED ENGINEER** Bio-Medical Scientist. PhD Wageningen.

ADVISORS **Prof. Tristan van Leeuwen**, Head of Computational Imaging, CWI. **Jean-Christophe Lonchamp**, ex-MD Intel Corporate Tech, ex-Director TSMC. **Cheryl Hartfield, FASM**, ex-Zeiss, ex-Oxford Instruments, founder Omniprobe.

USE OF FUNDS · €2M The €10M Seed gate	45% engineering · multi-modality platform v1, OEM integrations (Zeiss, ASI, Delmic). 30% commercial · pilot conversion, ISTFA launch, EU + US presence. 15% key hires · two hires only: commercial lead and ML engineer. 10% IP & ops. Seed gate: 3+ paid pilots as ARR · first OEM co-development signed · multi-modality platform live · EIC Accelerator application in for €2.5M non-dilutive EU funding layered in.
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